

N-Channel Depletion-Mode Vertical DMOS FET

Features

- High input impedance
- Low input capacitance
- ▶ Fast switching speeds
- Low on-resistance
- ▶ Free from secondary breakdown
- Low input and output leakage

Applications

- Normally-on switches
- Solid state relays
- Converters
- Linear amplifiers
- Constant current sources
- Telecom

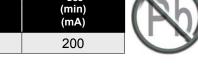
General Description

This depletion-mode (normally-on) transistor utilizes an advanced vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Ordering Information

Device	Package Option	BV _{DSX} /BV _{DGX}	R _{DS(ON)}	I _{DSS}									
Device	TO-252 (D-PAK)	(V)	(max) (Ω)	(min) (mA)									
DN3765	DN3765K4-G	650	8.0	200									





-G indicates package is RoHS compliant ('Green')

Absolute Maximum Ratings

Parameter	Value
Drain-to-source voltage	BV _{DSX}
Drain-to-gate voltage	BV_{DGX}
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C
Maximum junction temperature*	150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Pin Configuration



Product Marking



YY = Year Sealed
WW = Week Sealed
L = Lot Number
_____= "Green" Packaging

TO-252 (D-PAK) (K4)

^{*} Distance of 1.6mm from case for 10 seconds.

Thermal Characteristics

Package	I _D (continuous) [†] (A)	I _D (pulsed) (A)	Power Dissipation [‡] @T _A = 25°C (W)	θ _{jc} (°C/W)	θ _{ja} (°C/W)	† (A)	I _{DRM} (A)
TO-252 (D-PAK)	0.30	0.50	2.5	6.25	50	0.30	0.50

Notes:

- $I_{\rm D}$ (continuous) is limited by max rated $T_{\rm j}$ of 150°C. Mounted on FR4 board, 25mm x 25mm x 1.57mm.

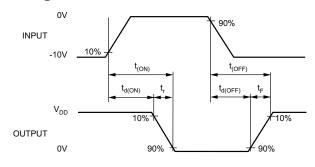
Electrical Characteristics (T_A = 25°C unless otherwise specified)

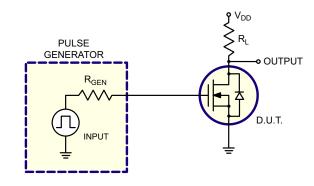
Sym	Parameter	Min	Тур	Max	Units	Conditions					
BV _{DSX}	Drain-to-source breakdown voltage	650	-	-	V	$V_{GS} = -5.0V, I_{D} = 100\mu A$					
$V_{GS(OFF)}$	Gate-to-source off voltage	-1.5	-	-3.5	V	$V_{DS} = 25V, I_{D} = 10\mu A$					
$\Delta V_{GS(OFF)}$	Change in V _{GS(OFF)} with temperature	-	-	-4.5	mV/°C	$V_{DS} = 25V, I_{D} = 10\mu A$					
I _{GSS}	Gate body leakage current	-	ı	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$					
		1	1	10	μA	$V_{GS} = -10V, V_{DS} = Max Rating$					
l _{D(OFF)}	Drain-to-source leakage current	-	-	1.0	mA	$V_{GS} = -10V, V_{DS} = 0.8 \text{ Max Rating},$ $T_A = 125^{\circ}\text{C}$					
I _{DSS}	Saturated drain-to-source current	200	-	-	mA	$V_{GS} = 0V, V_{DS} = 25V$					
R _{DS(ON)}	Static drain-to-source on-state resistance	-	-	8.0	Ω	$V_{GS} = 0V, I_D = 150mA$					
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with temperature	ı	ı	1.1	%/°C	$V_{GS} = 0V, I_D = 150mA$					
G _{FS}	Forward transductance	100	ı	-	mmho	$I_{D} = 100 \text{mA}, V_{DS} = 10 \text{V}$					
C _{ISS}	Input capacitance	-	-	825		V _{GS} = -10V,					
C _{oss}			ı	190	pF	V _{DS} = 25V,					
C _{RSS}	Reverse transfer capacitance	ı	ı	110		f = 1.0MHz					
t _{d(ON)}	Turn-on delay time	ı	ı	50		V 05V					
t _r	Rise time	-	-	75		$V_{DD} = 25V,$ $I_{D} = 150 \text{mA},$					
t _{d(OFF)}	Turn-off delay time	-	-	75	ns	$R_{GEN} = 25\Omega$					
t _f	Fall time	-	-	100		GEN 2012					
V _{SD}	Diode forward voltage drop	-	-	1.8	V	V _{GS} = -5.0V, I _{SD} = 200mA					
t _{rr}	Reverse recovery time	-	800	-	ns	$V_{GS} = -5.0V, I_{SD} = 200mA$					

Notes:

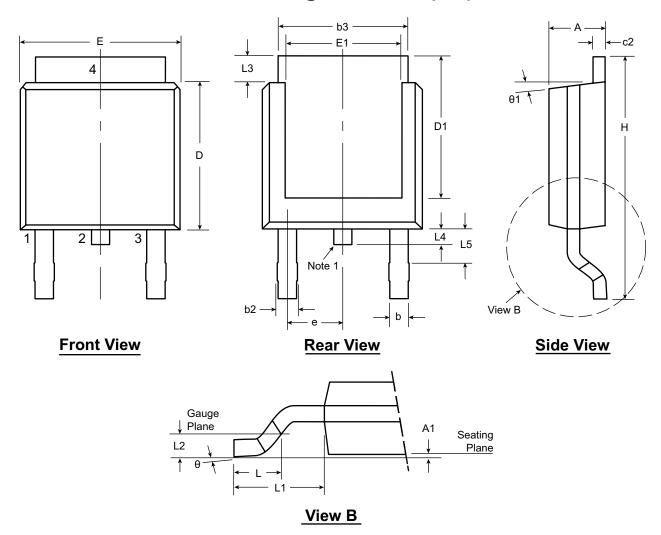
- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

Switching Waveforms and Test Circuit





3-Lead TO-252 D-PAK Package Outline (K4)



Note:

Although 4 terminal locations are shown, only 3 are functional. Lead number 2 was removed.

Symb	ol	A	A1	b	b2	b3	c2	D	D1	E	E1	е	Н	L	L1	L2	L3	L4	L5	θ	θ1
Dimen-	MIN	.086	.000*	.025	.030	.195	.018	.235	.205	.250	.170		.370	.055			.035	.025*	.045	0 º	00
sion	NOM	-	-	-	-	-	-	.240	-	-	-	.090 BSC	-	.060	.108 REF	.020 BSC	-	-	-	-	-
(inches)	MAX	.094	.005	.035	.045	.215	.035	.245	.217*	.265	.182*		.410	.070			.050	.040	.060	10º	15º

JEDEC Registration TO-252, Variation AA, Issue E, June 2004.

* This dimension is not specified in the original JEDEC drawing. The value listed is for reference only.

Drawings not to scale.

Supertex Doc. #: DSPD-3TO252K4, Version D081408.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

Supertex inc. does not recommend the use of its products in life support applications, and will not knowingly sell them for use in such applications unless it receives an adequate "product liability indemnification insurance agreement." Supertex inc. does not assume responsibility for use of devices described, and limits its liability to the replacement of the devices determined defective due to workmanship. No responsibility is assumed for possible omissions and inaccuracies. Circuitry and specifications are subject to change without notice. For the latest product specifications refer to the Supertex inc. website: http://www.supertex.com.

©2008 **Supertex inc.** All rights reserved. Unauthorized use or reproduction is prohibited

